



<b>Title of Change:</b>	Change of Mold compound in ON Semiconductor Tarlac, Philippines from CEL-314 to EME-G770HMD.							
<b>Proposed First Ship date:</b>	7 February 2020							
<b>Contact Information:</b>	Contact your local ON Semiconductor Sales Office or <keiji.ueda@onsemi.com>							
<b>Samples:</b>	Contact your local ON Semiconductor Sales Office or <PCN.samples@onsemi.com> Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change.							
<b>Type of Notification:</b>	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact <PCN.Support@onsemi.com>							
<b>Change Part Identification:</b>	Date Code							
<b>Change Category:</b>	<input type="checkbox"/> Wafer Fab Change <input checked="" type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input type="checkbox"/> Other _____							
<b>Change Sub-Category(s):</b>	<input type="checkbox"/> Manufacturing Site Addition <input checked="" type="checkbox"/> Material Change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Manufacturing Site Transfer <input type="checkbox"/> Product specific change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Other: _____							
<b>Sites Affected:</b>	ON Semiconductor Sites : ON Tarlac City, Philippines	External Foundry/Subcon Sites: None						
<b>Description and Purpose:</b>								
This initial notification announces the change of Mold compound from CEL-314 to EME-G770HMD in OSPI Tarlac.								
	<table border="1"> <thead> <tr> <th></th> <th>Before Change Description</th> <th>After Change Description</th> </tr> </thead> <tbody> <tr> <td>Mold Compound</td> <td>CEL-314</td> <td>EME-G770</td> </tr> </tbody> </table>			Before Change Description	After Change Description	Mold Compound	CEL-314	EME-G770
	Before Change Description	After Change Description						
Mold Compound	CEL-314	EME-G770						
No product marking, package dimension, electrical characteristic change as a result of this change.								



**Qualification Plan:**

**QV DEVICE NAME: LC898116A-TBM-H**

**RMS: 57801**

**PACKAGE: VQFN44K**

Test	Specification	Condition	Interval
HTOL	JESD22-A108	TA=150°C, bias at 1.2X Nominal (not to exceed Max rated)	1008 hrs
HTSL	JESD22-A103	Temp =150°C	1008 hrs
TC	JESD22-A104	Temp = -65°C to +150°C;	500 cyc
uHAST	JESD22-A118	Temp = 130C, RH=85%, ~18.8 psig	96 hrs
PC	J STD 020A, JESD22-A113	MSL 2 @ 260 °C	-
RSH	JESD22- B106	Ta = 265C, 10 sec	-
SD	JSTD002	Ta = 245C, 10 sec	-

Estimated date for qualification completion: **30 August 2019**

**List of Affected Parts:**

**Note:** Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [PCN Customized Portal](#).

Part Number	Qualification Vehicle
LC898116A-TBM-H	LC898116A-TBM-H
LC898116-TBM-H	



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## Appendix A: Changed Products

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Product	Customer Part Number	Qualification Vehicle
LC898116A-TBM-H		LC898116A-TBM-H